Photocouplers Infrared LED & Photo IC

TLP109(IGM)

1. Applications

- Intelligent Power Module Signal Isolation
- High-Speed Digital Interfacing for Instrumentation and Control Devices
- Industrial Inverters

2. General

The Toshiba TLP109(IGM) mini-flat coupler is a small-outline coupler suitable for surface-mount assembly. The TLP109(IGM) consists of an infrared LED optically coupled to a high-speed photodiode-transistor chip. The TLP109(IGM) is housed in the SO6 package and guarantees a creepage distance of ≥5.0 mm, a clearance of ≥5.0 mm and an insulation thickness of ≥0.4mm. Therefore, the TLP109(IGM) meets the reinforced insulation class requirements of international safety standards. The TLP109(IGM) guarantees minimum and maximum of propagation delay time, switching time dispersion, and high common mode transient immunity. Therefore TLP109 (IGM) is suitable for isolation interface between IPM(Intelligent Power Module) and control IC circuits in motor control application.

3. Features

(1) Isolation voltage: 3750 Vrms (min)

(2) Common-mode transient immunity: 10 kV/μs (min)
@V_{CM} = 1500 V_{p-p}

(3) Propagation delay time t_{pHL}/t_{pLH} = 0.1 μs (min)
= 0.8 μs (max)
@ I_F = 10 mA, V_{CC} = 15 V,
R_L = 20 kΩ, T_a = 25 °C

(4) Pulse width distortion: 0.7 μs (max) ($|t_{pHL}-t_{pLH}|$)

(5) TTL compatible

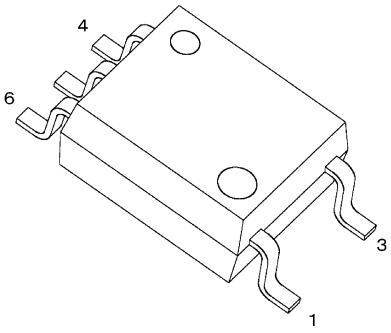
(6) Safety standards
UL-recognized: UL 1577, File No.E67349
cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349
VDE-approved: EN 60747-5-5, EN 62368-1 **(Note 1)**
CQC-approved: GB4943.1, GB8898 Thailand Factory

仅适用于海拔 2000m 以下地区安全使用

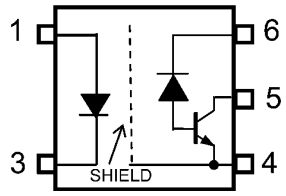
Note 1: When a VDE approved type is needed, please designate the **Option (V4)**.

Start of commercial production
2008-07

4. Packaging and Pin Assignment

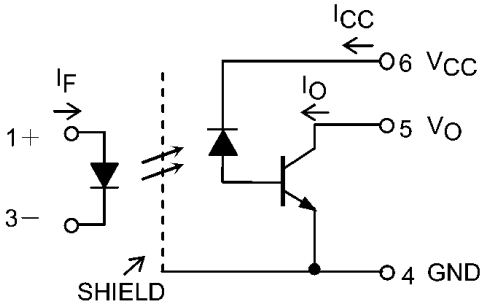


11-4L1S



1: Anode
3: Cathode
4: GND
5: V_O (Output)
6: V_{CC}

5. Internal Circuit



6. Principle of Operation

6.1. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	5.0	mm
Clearance distances	5.0	
Internal isolation thickness	0.4	

7. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I_F		20	mA
	Input forward current derating	($T_a \geq$ 95 °C)	$\Delta I_F/\Delta T_a$		-0.36	mA/°C
	Input forward current (pulsed)		I_{FP}	(Note 1)	40	mA
	Peak transient input forward current		I_{FPT}	(Note 2)	1	A
	Input reverse voltage		V_R		5	V
	Input power dissipation		P_D		40	mW
	Input power dissipation derating	($T_a \geq$ 95 °C)	$\Delta P_D/\Delta T_a$		-0.72	mW/°C
	Junction temperature		T_j		125	°C
Detector	Output current		I_O		8	mA
	Output current derating	($T_a \geq$ 95 °C)	$\Delta I_O/\Delta T_a$		-0.3	mA/°C
	Peak output current		I_{OP}		16	mA
	Output voltage		V_O		-0.5 to 20	V
	Supply voltage		V_{CC}		-0.5 to 30	V
	Output power dissipation		P_O		100	mW
	Output power dissipation derating	($T_a \geq$ 95 °C)	$\Delta P_O/\Delta T_a$		-1.8	mW/°C
	Junction temperature		T_j		125	°C
Common	Operating temperature		T_{opr}		-55 to 125	
	Storage temperature		T_{stg}		-55 to 125	
	Lead soldering temperature	(10 s)	T_{sol}		260	
	Isolation voltage	(AC, 60 s, R.H. ≤ 60 %)	BV_S	(Note 3)	3750	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) ≤ 1 ms, duty = 50 %

Note 2: Pulse width (PW) ≤ 1 μs, 300 pps

Note 3: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

8. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Input forward voltage	V_F			I_F = 16 mA	1.5	1.64	1.85	V
Input forward voltage temperature coefficient	$\Delta V_F/\Delta T_a$			I_F = 16 mA	—	-1.8	—	mV/°C
Input reverse current	I_R			V_R = 3 V	—	—	10	μA
Input capacitance	C_t			V = 0 V, f = 1 MHz	—	60	—	pF
High-level output current	I_{OH}			I_F = 0 mA, V_O = V_{CC} = 5.5 V	—	3	500	nA
				I_F = 0 mA, V_O = 20 V, V_{CC} = 30 V	—	—	5	μA
				I_F = 0 mA, V_O = 20 V, V_{CC} = 30 V, T_a = 100 °C	—	—	50	
High-level supply current	I_{CCH}			I_F = 0 mA, V_{CC} = 30 V	—	0.01	1	μA
Supply voltage	V_{CC}			I_{CC} = 0.01 mA	30	—	—	V
Output voltage	V_O			I_O = 0.5 mA	20	—	—	V

9. Coupled Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	I_O/I_F	I_F = 10 mA, V_{CC} = 4.5 V, V_O = 0.4 V	25	35	75	%
		I_F = 10 mA, V_{CC} = 4.5 V, V_O = 0.4 V, T_a = -25 to 100 °C	15	—	—	
Low-level output voltage	V_{OL}	I_F = 16 mA, V_{CC} = 4.5 V, I_O = 2.4 mA	—	—	0.4	V

10. Isolation Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Conditions	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	V_S = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation resistance	R_S	(Note 1)	V_S = 500 V, R.H. ≤ 60 %	10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	3750	—	—	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4, 5 and 6 are shorted together.

11. Switching Characteristics (Unless otherwise specified, T_a = 25 °C, V_{CC} = 15 V)

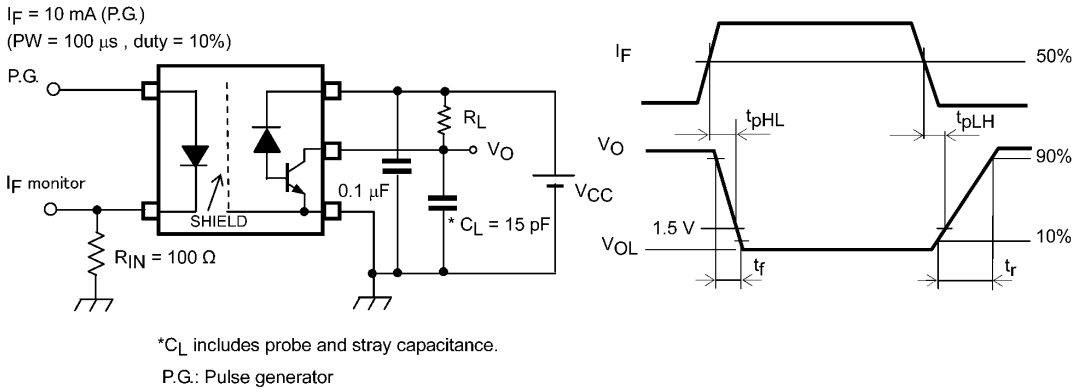
Characteristics	Symbol	Note	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Propagation delay time (H/L)	t_{pHL}		Fig.12.1.1	I_F = 10 mA, R_L = 20 kΩ	0.1	0.45	0.8	μs
				I_F = 10 mA, R_L = 20 kΩ, T_a = 0 to 85 °C	0.1	0.45	0.9	
				I_F = 10 mA, R_L = 20 kΩ, T_a = -25 to 100 °C	0.1	0.45	1.0	
Propagation delay time (L/H)	t_{pLH}		Fig.12.1.1	I_F = 10 mA, R_L = 20 kΩ	0.1	0.45	0.8	μs
				I_F = 10 mA, R_L = 20 kΩ, T_a = 0 to 85 °C	0.1	0.45	0.9	
				I_F = 10 mA, R_L = 20 kΩ, T_a = -25 to 100 °C	0.1	0.45	1.0	
Pulse width distortion	$\lvert t_{pHL}-t_{pLH}\rvert$		Fig.12.1.1	I_F = 10 mA, R_L = 20 kΩ	—	0.15	0.7	μs
				I_F = 10 mA, R_L = 20 kΩ, T_a = 0 to 85 °C	—	0.25	0.8	
				I_F = 10 mA, R_L = 20 kΩ, T_a = -25 to 100 °C	—	0.25	0.9	
High-level common-mode transient immunity	CM_H	(Note 1)	Fig.12.1.2	V_{CM} = 1500 V_{p-p}, I_F = 0 mA, R_L = 20 kΩ	10	15	—	kV/μs
Low-level common-mode transient immunity	CM_L	(Note 2)		V_{CM} = 1500 V_{p-p}, I_F = 10 mA, R_L = 20 kΩ	-10	-15	—	kV/μs

Note 1: CM_H is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state (V_O > 4 V).

Note 2: CM_L is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state (V_O < 1 V).

12. Test Circuits and Characteristics Curves

12.1. Test Circuits



*C_L includes probe and stray capacitance.

P.G.: Pulse generator

Fig. 12.1.1 Switching Time Test Circuit and Waveform

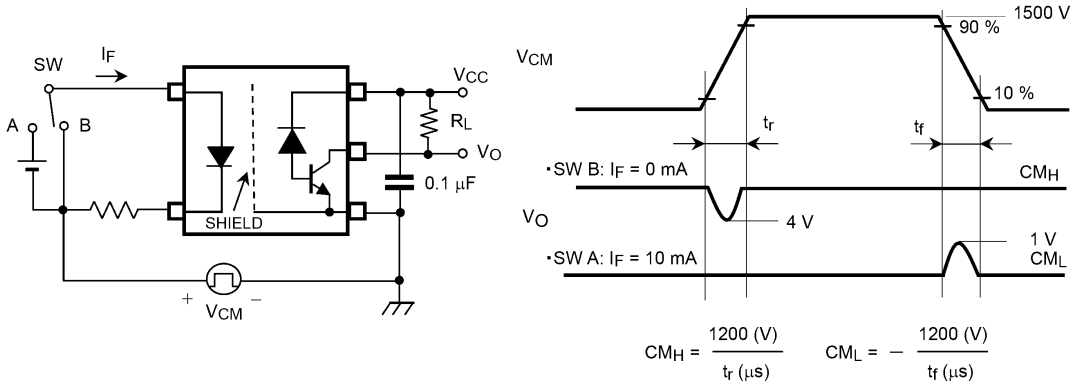


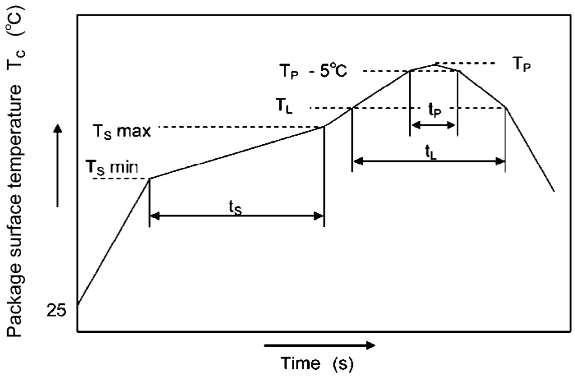
Fig. 12.1.2 Common-Mode Transient Immunity Test Circuit and Waveform

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.
  The soldering temperature profile is based on the package surface temperature.
  (See the figure shown below, which is based on the package surface temperature.)
  Reflow soldering must be performed once or twice.
  The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	T_S	150	200	°C
Preheat time	t_S	60	120	s
Ramp-up rate (T_L to T_P)			3	°C/s
Liquidus temperature	T_L	217		°C
Time above T_L	t_L	60	150	s
Peak temperature	T_P		260	°C
Time during which T_c is between (T_P – 5) and T_P	t_P		30	s
Ramp-down rate (T_P to T_L)			6	°C/s

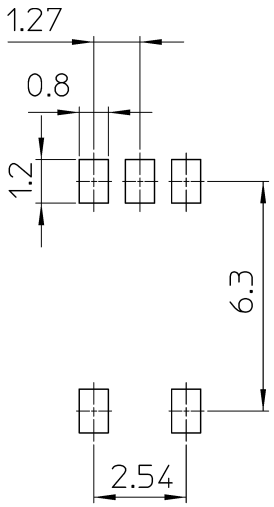
An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

- When using soldering flow
  Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
  Mounting condition of 260 °C within 10 seconds is recommended.
  Flow soldering must be performed once.
- When using soldering Iron
  Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
  Heating by soldering iron must be done only once per lead.

13.2. Precautions for General Storage

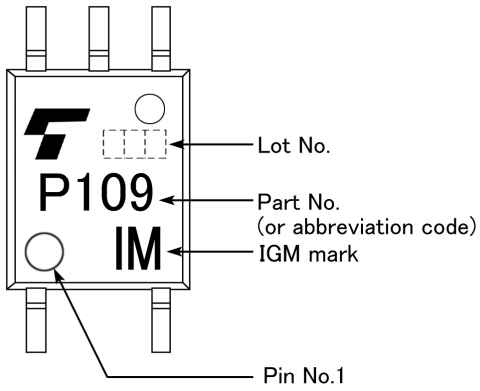
- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Land Pattern Dimensions (for reference only)



Unit: mm

15. Marking



16. EN 60747-5-5 Option (V4) Specification

- Part number: TLP109 **(Note 1)**
- The following part naming conventions are used for the devices that have been qualified according to option (V4) of EN 60747.

  Example: TLP109(V4IGMTL,E

  V4: EN 60747 option
  IGM: IGM spec
  TL: Tape type
  E: [[G]]/RoHS COMPATIBLE **(Note 2)**

Note 1: Use TOSHIBA standard type number for safety standard application.
e.g., TLP109(V4IGMTL,E → TLP109

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.
RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Description	Symbol	Rating	Unit
Application classification for rated mains voltage ≤ 150 Vrms for rated mains voltage ≤ 300 Vrms		 I-IV I-III	—
Climatic classification		55 / 125 / 21	—
Pollution degree		2	—
Maximum operating insulation voltage	V_{IORM}	707	Vpeak
Input to output test voltage, Method A V_{pr} = 1.6 × V_{IORM}, type and sample test t_p = 10 s, partial discharge < 5 pC	V_{pr}	1131	Vpeak
Input to output test voltage, Method B V_{pr} =1.875 × V_{IORM}, 100 % production test t_p = 1 s, partial discharge < 5 pC	V_{pr}	1330	Vpeak
Highest permissible overvoltage (transient overvoltage, t_{pr} = 60 s)	V_{TR}	6000	Vpeak
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current I_F, P_{so} = 0) power (output or total power dissipation) temperature	 I_{si} P_{so} T_s	 250 400 150	 mA mW °C
Insulation resistance V_{IO} = 500 V, T_a = 25 °C V_{IO} = 500 V, T_a = 100 °C V_{IO} = 500 V, T_a = T_s	R_{si}	≥ 10^{12} ≥ 10^{11} ≥ 10^{9}	Ω

Fig. 16.1 EN 60747 Isolation Characteristics

Minimum creepage distance	Cr	5.0 mm
Minimum clearance	Cl	5.0 mm
Minimum insulation thickness	ti	0.4 mm
Comparative tracking index	CTI	175

Fig. 16.2 Insulation Related Specifications (Note)

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.

Fig. 16.3 Marking on Packing

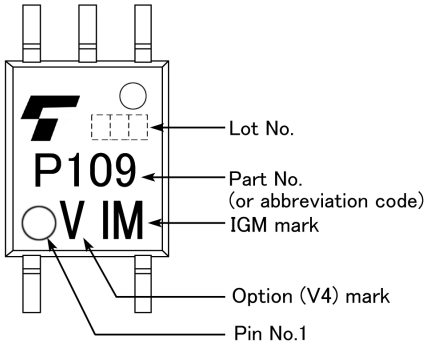


Fig. 16.4 Marking Example (Note)

Note: The above marking is applied to the photocouplers that have been qualified according to option (V4) of EN 60747.

Figure 1 Partial discharge measurement procedure according to EN 60747
Destructive test for qualification and sampling tests.

Method A

(for type and sampling tests, destructive tests)

t_1, t_2	= 1 to 10 s
t_3, t_4	= 1 s
t_p (Measuring time for partial discharge)	= 10 s
t_b	= 12 s
t_{ini}	= 60 s

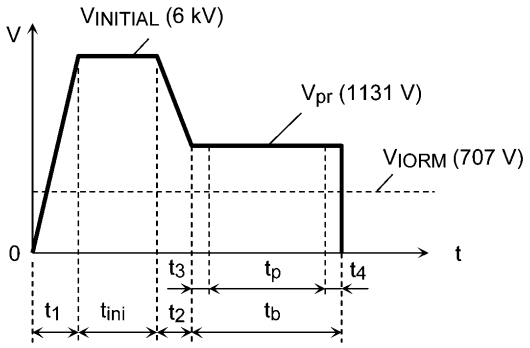


Figure 2 Partial discharge measurement procedure according to EN 60747
Non-destructive test for 100 % inspection.

Method B

(for sample test,non-destructive test)

t_3, t_4	= 0.1 s
t_p (Measuring time for partial discharge)	= 1 s
t_b	= 1.2 s

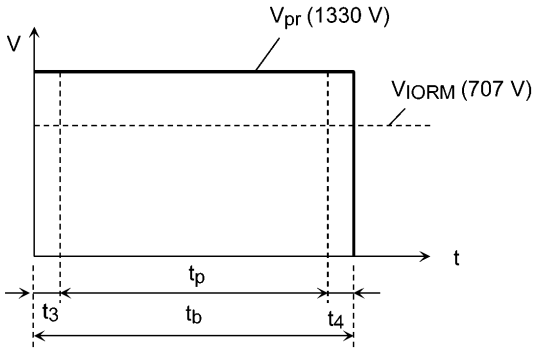


Figure 3 Dependency of maximum safety ratings on ambient temperature

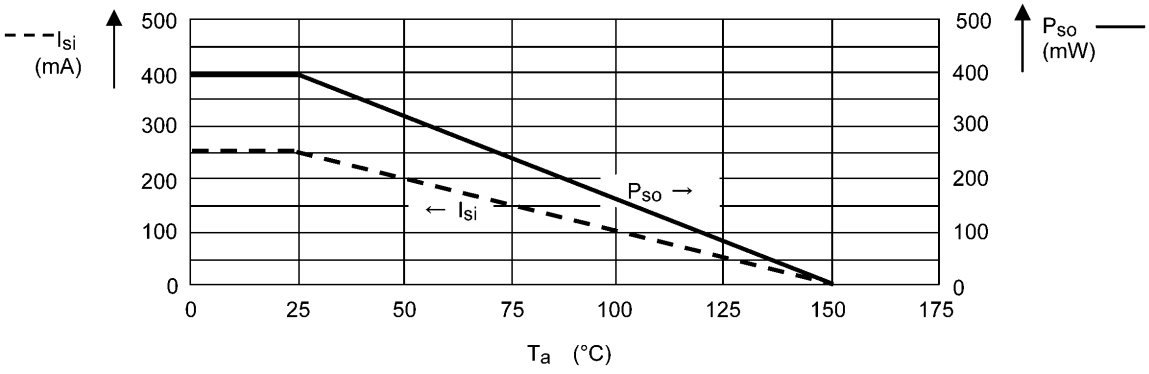


Fig. 16.5 Measurement Procedure

17. Ordering Information

When placing an order, please specify the part number, tape type and quantity as shown in the following example.

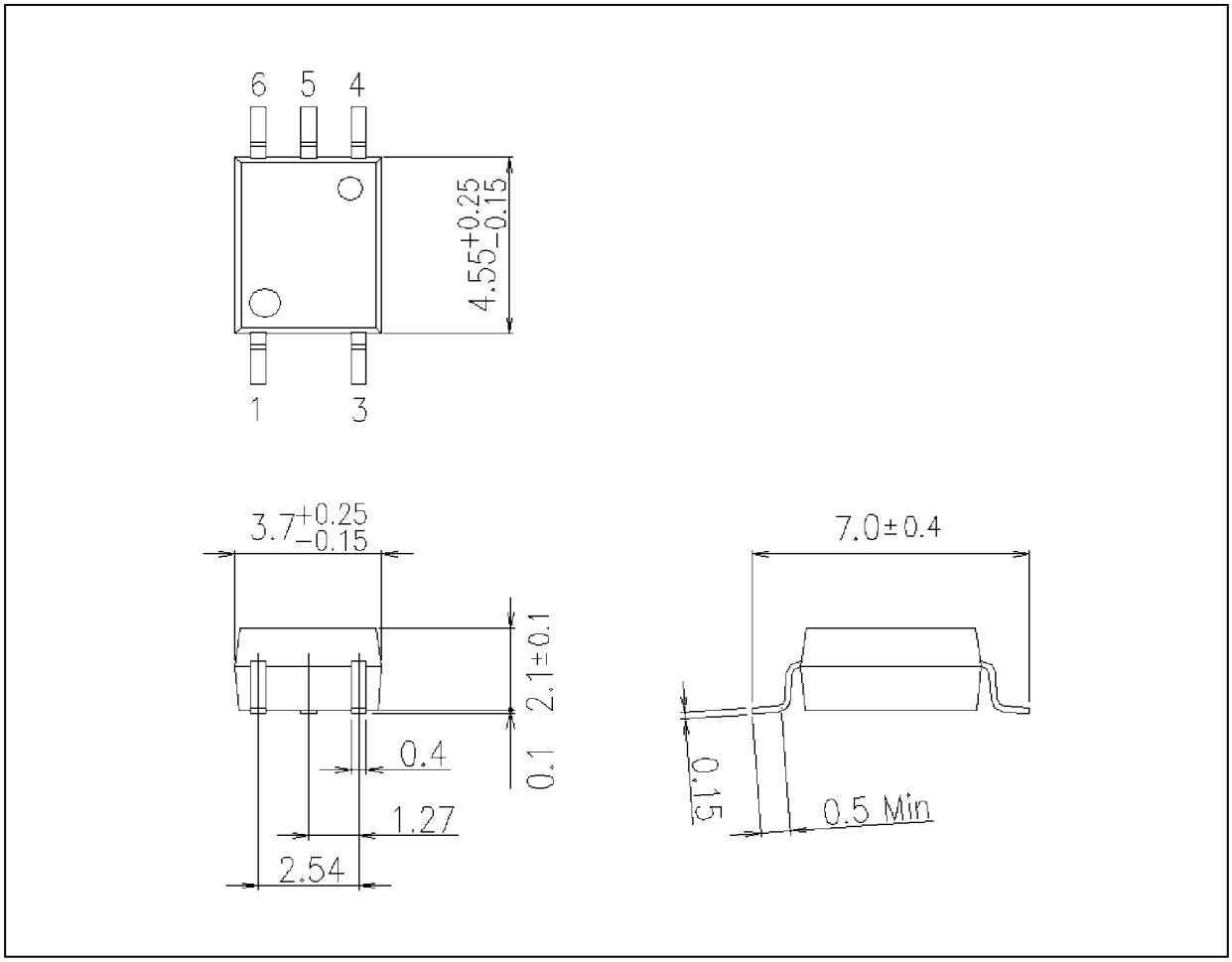
Example) TLP109(IGM-TPL,E 3000 pcs

Part number: TLP109
IGM spec: IGM
Tape type: TPL
[[G]]/RoHS COMPATIBLE: E **(Note 1)**
Quantity (must be a multiple of 3000): 3000 pcs

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.
RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Package Dimensions

Unit: mm



Weight: 0.08 g (typ.)

Package Name(s)
TOSHIBA: 11-4L1S

RESTRICTIONS ON PRODUCT USE

Toshiba Corporation and its subsidiaries and affiliates are collectively referred to as "TOSHIBA".
Hardware, software and systems described in this document are collectively referred to as "Product".

- TOSHIBA reserves the right to make changes to the information in this document and related Product without notice.
- This document and any information herein may not be reproduced without prior written permission from TOSHIBA. Even with TOSHIBA's written permission, reproduction is permissible only if reproduction is without alteration/omission.
- Though TOSHIBA works continually to improve Product's quality and reliability, Product can malfunction or fail. Customers are responsible for complying with safety standards and for providing adequate designs and safeguards for their hardware, software and systems which minimize risk and avoid situations in which a malfunction or failure of Product could cause loss of human life, bodily injury or damage to property, including data loss or corruption. Before customers use the Product, create designs including the Product, or incorporate the Product into their own applications, customers must also refer to and comply with (a) the latest versions of all relevant TOSHIBA information, including without limitation, this document, the specifications, the data sheets and application notes for Product and the precautions and conditions set forth in the "TOSHIBA Semiconductor Reliability Handbook" and (b) the instructions for the application with which the Product will be used with or for. Customers are solely responsible for all aspects of their own product design or applications, including but not limited to (a) determining the appropriateness of the use of this Product in such design or applications; (b) evaluating and determining the applicability of any information contained in this document, or in charts, diagrams, programs, algorithms, sample application circuits, or any other referenced documents; and (c) validating all operating parameters for such designs and applications. **TOSHIBA ASSUMES NO LIABILITY FOR CUSTOMERS' PRODUCT DESIGN OR APPLICATIONS.**
- PRODUCT IS NEITHER INTENDED NOR WARRANTED FOR USE IN EQUIPMENTS OR SYSTEMS THAT REQUIRE EXTRAORDINARILY HIGH LEVELS OF QUALITY AND/OR RELIABILITY, AND/OR A MALFUNCTION OR FAILURE OF WHICH MAY CAUSE LOSS OF HUMAN LIFE, BODILY INJURY, SERIOUS PROPERTY DAMAGE AND/OR SERIOUS PUBLIC IMPACT ("UNINTENDED USE").
  Except for specific applications as expressly stated in this document, Unintended Use includes, without limitation, equipment used in nuclear facilities, equipment used in the aerospace industry, lifesaving and/or life supporting medical equipment, equipment used for automobiles, trains, ships and other transportation, traffic signaling equipment, equipment used to control combustions or explosions, safety devices, elevators and escalators, and devices related to power plant.
  IF YOU USE PRODUCT FOR UNINTENDED USE, TOSHIBA ASSUMES NO LIABILITY FOR PRODUCT.
  For details, please contact your TOSHIBA sales representative or contact us via our website.
- Do not disassemble, analyze, reverse-engineer, alter, modify, translate or copy Product, whether in whole or in part.
- Product shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable laws or regulations.
- The information contained herein is presented only as guidance for Product use. No responsibility is assumed by TOSHIBA for any infringement of patents or any other intellectual property rights of third parties that may result from the use of Product. No license to any intellectual property right is granted by this document, whether express or implied, by estoppel or otherwise.
- **ABSENT A WRITTEN SIGNED AGREEMENT, EXCEPT AS PROVIDED IN THE RELEVANT TERMS AND CONDITIONS OF SALE FOR PRODUCT, AND TO THE MAXIMUM EXTENT ALLOWABLE BY LAW, TOSHIBA (1) ASSUMES NO LIABILITY WHATSOEVER, INCLUDING WITHOUT LIMITATION, INDIRECT, CONSEQUENTIAL, SPECIAL, OR INCIDENTAL DAMAGES OR LOSS, INCLUDING WITHOUT LIMITATION, LOSS OF PROFITS, LOSS OF OPPORTUNITIES, BUSINESS INTERRUPTION AND LOSS OF DATA, AND (2) DISCLAIMS ANY AND ALL EXPRESS OR IMPLIED WARRANTIES AND CONDITIONS RELATED TO SALE, USE OF PRODUCT, OR INFORMATION, INCLUDING WARRANTIES OR CONDITIONS OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, ACCURACY OF INFORMATION, OR NONINFRINGEMENT.**
- GaAs (Gallium Arsenide) is used in Product. GaAs is harmful to humans if consumed or absorbed, whether in the form of dust or vapor. Handle with care and do not break, cut, crush, grind, dissolve chemically or otherwise expose GaAs in Product.
- Do not use or otherwise make available Product or related software or technology for any military purposes, including without limitation, for the design, development, use, stockpiling or manufacturing of nuclear, chemical, or biological weapons or missile technology products (mass destruction weapons). Product and related software and technology may be controlled under the applicable export laws and regulations including, without limitation, the Japanese Foreign Exchange and Foreign Trade Law and the U.S. Export Administration Regulations. Export and re-export of Product or related software or technology are strictly prohibited except in compliance with all applicable export laws and regulations.
- Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. Please use Product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. **TOSHIBA ASSUMES NO LIABILITY FOR DAMAGES OR LOSSES OCCURRING AS A RESULT OF NONCOMPLIANCE WITH APPLICABLE LAWS AND REGULATIONS.**

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for High Speed Optocouplers ***category:***

Click to view products by Toshiba ***manufacturer:***

Other Similar products are found below :

TLP558(F) JAN4N24 610737H HCPL2630M HCPL2731SM HCPL2630SM PS9817A-1-F3-AX EL816S2(C)(TU)-F TLP281-4 TLP290(V4GBTP,SE(T PS9121-F3-AX PS9123-F3-AX TLP5774H(TP4,E TLP5771H(TP,E HCPL2531S HCPL2631SD HCPL-4661-500E TLP118(TPL,E) TLP521-2XGB TLP621-2XGB 4N46-300E JANTXV4N24U SFH6318T 6N135-300E TIL198 TLP2309(TPL,E) TLP2355(TPL,E TLP2391(E(T TLP521-4GR TLP521-4XGB TLP621-4X TLP621XSM IS281-4GB IS2805-4 IS181GR ICPL2631 ICPL2630 ICPL2531 ICPL2601 TLP714(F) TLP754(F) FOD260LSDV ACPL-M21L-500E ACPL-064L-500E PS2501-1XSM PS2505-1 PS2913-1-F3-AX PS9821-2-F3-AX FOD0721R2 FODM8061R2V